THERMAL SYSTEMS

New application possibilities with ProtectoXP

From Dam & Fill to the sealing loop – individually and precisely

Now even more *flexible!*



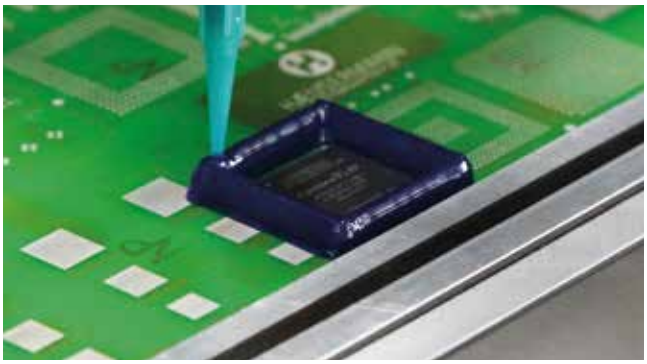

ProtectoXP
Coating

More than “just” coating
Application possibilities with ProtectoXP

With the ProtectoXP, completely new application fields are emerging – even outside of the conformal coating sector. Thanks to the highly flexible system construction, you can use ProtectoXP to combine several processes within one machine. In addition to sealing the entire circuit board, partial areas or individual components can also be coated on the support. From the “Globe Top” to “Dam & Fill” to the “Flip Chip Underfill”; different procedures have been developed here. With the ProtectoXP, a large number of applications – all in one system – can be realized. With innovative nozzle technology, the user can apply a wide variety of materials to the module – so each product will be optimally protected later according to the requirements.

Dam & Fill

Dam & Fill allows individual areas to be selectively coated on the circuit board, thereby efficiently protecting them. Two materials with different viscosities are used for this purpose. First, a dam is placed around the component to be protected with a highly viscous material. Subsequently, the region within the dam is filled with a low-viscosity material.



Sealing

In this process, a 1K or 2K material is applied to a component such that a continuous and uniform sealing loop is produced. Volumetric applicators are particularly suitable for this purpose.

Globe Top

A Globe Top is used to protect a selective area on the circuit board. For this purpose, a material is used which, on the one hand, is fluid enough to securely encapsulate all the components involved, but on the other hand, is not so low in viscosity that it flows onto adjacent components.

Highlights in ProtectoXP

Flip Chip Underfill

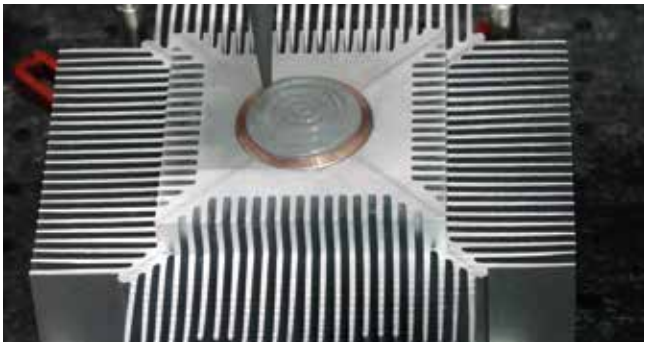
Underfills increase the mechanical stability between the chip and the circuit board and distribute locally occurring voltages over a larger area, which significantly increases the service life. For this purpose, a low-viscosity material is applied along the edge region of the chip, which then independently fills the gap between the chip and the circuit board using the capillary effect.

1K and 2K encapsulation

Encapsulation is always used when a particularly high level of protection is needed. Thanks to the volumetric applicators, it is ensured that exactly the same amount of material is always supplied in the correct mixing ratio, independent of temperature and pressure fluctuations.

Heat dissipation

Due to the constant miniaturisation in electronics, less and less surface is available for heat dissipation. This makes it all the more important to have an optimal passage between the heat sink and the component. Liquid heat-transfer media can be adapted to the individual contours better than fixed pads or foils and ensure a safe heat dissipation, which significantly increases the service life of the components.



Individual requirements

Are you looking for a partner who can offer you a complete solution for your coating and dispensing process? Then you've come to the right place! Thanks to versatile applicators and conveyor units, we are standing ready to meet many requirements with our standard applications. We are also prepared to tackle new challenges and to implement them for you in a series-production process.

THERMAL SYSTEMS

Rehm Worldwide

As a leading manufacturer of innovative thermal system solutions we have customers on every continent. With our own locations in Europe, America and Asia as well as 26 agencies in 24 countries we are able to serve the international markets quickly and to offer outstanding on-site service – worldwide and round the clock!

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